A1 INITIAL SCHEMATIC  04-08-2011  A1Y
A2 REMOVED ANALOG SWITCHES  05-12-2011  AKS
CHANGED FEEDBACK
A3 CHANGED THE SIZE OF THE SENSE RESISTORS  05-25-2011  AKS
ADDED PULL-UP/PULL-DOWN ON SPI LINES
REMOVED 0-OM RESISTORS ON CURRENT SENSE
B1 FIXED DRV8301 CURRENT SENSE POLARITY  07-14-2011  JPW
NO-POP ALL EXTERNAL CURRENT SENSE COMPONENTS
CHANGED C14 TO 25V 0805 PACKAGE
FETS CHANGED TO VISHAY SUI10N06-3M9H
CHANGED CURRENT SENSE RESISTORS TO 2mOHM
RECONFIGURED DC BUS CAPS
SPLIT POWER CONNECTOR INTO TWO CONNECTORS
C1 LAYOUT CHANGES TO IMPROVE GROUND CONNECTIONS FOR  08-12-2011  AKS
DE-COUPLING CAPACITORS C10, C14, C72
CREATED BOM VARIANT FOR DRV8302
CHANGED R12, R13, R21 TO 1K
CHANGED R43, R47 TO 1K (DRV8302 ONLY)
D1 POPULATED EXTERNAL GAIN OP-AMPS AND CHANGED  01-18-2012
CONNECTIONS FOR THESE TO DAUGHTER CARD

Notes - Unless otherwise noted
1. Resistances values in Ohms
2. Capacitance values in microfarads (uF)
3. All 0.1uF and 0.01uF capacitors are decoupling and should be placed
near the IC they are shown with.

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Page 6 - Power Input - Voltage Regulators - Current Sense Amplifiers
Page 7 - Half Bridges - Motor Output
Kelvin connections used on all current sense resistors
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